

IEC 62153-4-3

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# INTERNATIONAL STANDARD



Metallic communication cable test methods – Part 4-3: Electromagnetic compatibility (EMC) related test method for measuring surface transfer impedance – Triaxial method

INTERNATIONAL ELECTROTECHNICAL COMMISSION

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### - 2 - IEC 62153-4-3:2013+AMD1:2024 CSV © IEC 2024

### **CONTENTS**

FOF	FOREWORD5				
INT	INTRODUCTION7				
1	Scope				
2	Norm	ative re	ferences	9	
3	Term	s and de	efinitions	9	
4	Princ	iple		. 12	
5	Test methods				
	5.1				
			puipment		
	5.3		tion procedure		
	5.4		preparation		
	5.5	Test se	t-up	.14	
	5.6	Test co	onfigurations	. 15	
		5.6.1	General	. 15	
		5.6.2	Vector network analyser with S-parameter test set	15	
		5.6.3	(Vector) network analyser with power splitter	16	
		5.6.4	Separate signal generator and receiver		
	5.7	Expres	sion of test results	17	
		5.7.1	Expression		
		5.7.2	Test report		
6	Test		A: Matched inner circuit with damping resistor in outer circuit		
	6.1		ll		
	6.2		ng resistor R <sub>2</sub>		
	6.3		frequency		
	6.4		liagram of the set-up		
	6.5		ring procedure		
7	6.6		tion of test results	. 19	
7			B: Inner circuit with load resistor and outer circuit without damping	. 19	
	7.1	Genera	ıl	. 19	
	7.2		frequency		
	7.3	Block d	liagram of the set-up	19	
	7.4	Measu	ing procedure	.20	
	7.5	Evalua	tion of test results	21	
8	Test	method	C: (Mismatched)-Short-Short without damping resistor	21	
	8.1	Genera	ıl	.21	
	8.2	Cut-off	frequency	.21	
	8.3	Block d	liagram of the set-up	22	
	8.4		ring procedure		
	8.5		tion of test results		
Ann	ex A		ive) Determination of the impedance of the inner circuit		
	A.1	Impeda	ince of inner circuit	. 24	
Ann	ex B	(normati	ive) Impedance matching adapter	25	
	B.1	Design	of the impedance matching circuit	25	
		B.1.1	General		
		B.1.2	Secondary impedance $\mathbb{Z}_2$ lower than primary impedance $\mathbb{Z}_1$	25	

IEC 62153-4-3:2013+AMD1:2024 CSV - 3 - © IEC 2024

REDLINE VERSION

	B.1.3 Secondary impedance $\mathbb{Z}_2$ higher than primary impedance $\mathbb{Z}_1$	26	
B.2	Frequency response of the impedance matching circuit	26	
	B.2.1 General	26	
	B.2.2 Measurement using two identical impedance matching adapters	27	
	B.2.3 Measurement using the open/short method	27	
	B.2.4 Example of a coaxial 50 $\Omega$ to 75 $\Omega$ impedance matching adapter	27	
Annex C (normative) Sample preparation for "milked on braid" method			
C.1	General	29	
C.2	Coaxial cables		
C.3	Symmetrical and multiconductor cables		
C.4	Verification of the sample preparation with TDR		
Annex D	(informative) Triaxial test set-up depicted as a T-circuit		
D.1	General		
D.2	Scattering parameter $S_{21}$ of the T-circuit	36	
	(informative) Cut-off frequency of the triaxial set-up for the measurement of fer impedance	37	
E.1	Equivalent circuit	37	
E.2	Coupling equations	37	
E.3	Cut-off frequency		
E.4	Determination of the dielectric permittivity and impedance		
Annex F	(informative) Impact of ground loops on low frequency measurements	43	
F.1	General		
F.2	Analysis of the test set-up [3]	43	
	(normative) Single pair cables – Conversion of measured mixed mode g parameters to transfer impedance	16	
G.1	General		
G.1 G.2	Conversion formula for test method B: Inner circuit with load resistor and	40	
G.2	outer circuit without damping resistor	46	
Bibliogra	phy		
Figure 1	– Definition of Z <sub>T</sub>	10	
Figure 2	– Definition of Z <sub>F</sub>	11	
	Preparation of test sample for coaxial cables		
_	– Preparation of test sample for symmetrical cables		
	- Connection to the tube		
	<ul> <li>Test set-up using a vector network analyser with the S-parameter test set</li> </ul>		
_	$-$ 50 $\Omega$ power splitter, 2- and 3-resistor types		
	<ul> <li>Test set-up using a network analyser (NA) and a power splitter</li> </ul>		
_	<ul> <li>Test set-up using a signal generator and a receiver</li> </ul>		
Figure 10	) – Test set-up using a signal generator and a receiver with feeding resistor	17	
Figure 1	l – Test set-up (principle)	18	
Figure 12	2 – Test set-up (principle)	20	
Figure 13	3 – Test set-up (principle)	22	
Figure B.	1 – Impedance matching for $Z_2 < Z_1$	25	
	2 – Impedance matching for $Z_2 > Z_1$		
	$3$ – Coaxial impedance matching adapters (50 $\Omega$ to 75 $\Omega$ )		
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# - 4 - IEC 62153-4-3:2013+AMD1:2024 CSV © IEC 2024

Figure B.4 – Attenuation of 50 $\Omega$ to 75 $\Omega$ impedance matching adapter	28
Figure C.1 – Coaxial cables: preparation of cable end "A" (1 of 2)	30
Figure C.2 – Coaxial cables: preparation of cable end "B"	32
Figure C.3 – Symmetrical cables: preparation of cable end "A" (1 of 2)	33
Figure C.4 – Symmetrical cables: preparation of cable end "B"	34
Figure C.5 – Typical resonance of end "A"	35
Figure C.6 – Typical resonance of end "B"	35
Figure D.1 – Triaxial set-up depicted as a T-circuit	36
Figure E.1 – Equivalent circuit of the triaxial set-up	37
Figure E.2 – Frequency response of the triaxial set-up for different load conditions	39
Figure E.3 – Measurement of $S_{11}$ of the outer circuit (tube) having a length of 50 cm	41
Figure F.1 – Triaxial test set-up	43
Figure F.2 – Equivalent circuits of the triaxial set-up	44
Figure F.3 – Example showing the impact of the measurement error	45

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## METALLIC COMMUNICATION CABLE TEST METHODS –

# Part 4-3: Electromagnetic compatibility (EMC) – Surface transfer impedance – Triaxial method

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This edition includes the following significant technical changes with respect to the previous edition:

- a) now three different test configurations are described;
- b) formulas to calculate the maximum frequency up to which the different test configurations can be used are included (Annex E: Cut-off frequency of the triaxial set-up for the measurement of the transfer impedance);
- c) the effect of ground loops is described (Annex F: impact of ground loops on low frequency measurements).

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62153 series, published under the general title *Metallic* communication cable test methods, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

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IEC 62153 consists of the following parts, under the general title *Metallic communication* cable test methods:

- Part 1-1: Metallic communication cables test methods Part 1-1: Electrical Measurement of the pulse/step return loss in the frequency domain using the Inverse Discrete Fourier Transformation (IDFT)
- Part 1-2: Metallic communication cables test methods Part 1-2: Electrical Reflection measurement correction<sup>1</sup>
- Part 4-0: Metallic communication cable test methods Part 4-0: Electromagnetic compatibility (EMC) Relationship between surface transfer impedance and screening attenuation, recommended limits
- Part 4-1: Metallic communication cable test methods Part 4-1: Electromagnetic compatibility (EMC) Introduction to electromagnetic (EMC) screening measurements
- Part 4-2: Metallic communication cable test methods Part 4-2: Electromagnetic compatibility (EMC) Screening and coupling attenuation Injection clamp method
- Part 4-3: Metallic communication cable test methods Part 4-3: Electromagnetic compatibility (EMC) Surface transfer impedance Triaxial method
- Part 4-4: Metallic communication cable test methods Part 4-4: Electromagnetic compatibility (EMC) Shielded screening attenuation, test method for measuring of the screening attenuation as up to and above 3 GHz
- Part 4-5: Metallic communication cables test methods Part 4-5: Electromagnetic compatibility (EMC) Coupling or screening attenuation Absorbing clamp method
- Part 4-6: Metallic communication cable test methods Part 4-6: Electromagnetic compatibility (EMC) Surface transfer impedance Line injection method
- Part 4-7: Metallic communication cable test methods Part 4-7: Electromagnetic compatibility (EMC) Test method for measuring the transfer impedance and the screening or the coupling attenuation Tube in tube method
- Part 4-8: Metallic communication cable test methods Part 4-8: Electromagnetic compatibility (EMC) Capacitive coupling admittance
- Part 4-9: Metallic communication cable test methods Part 4-9: Electromagnetic compatibility (EMC) Coupling attenuation of screened balanced cables, triaxial method
- Part 4-10: Metallic communication cable test methods Part 4-10: Electromagnetic compatibility (EMC) Shielded screening attenuation test method for measuring the screening effectiveness of feed-throughs and electromagnetic gaskets double coaxial method
- Part 4-11: Metallic communication cable test methods Part 4-11: Electromagnetic compatibility (EMC) Coupling attenuation or screening attenuation of patch cords, coaxial cable assemblies, pre-connectorized cables Absorbing clamp method

<sup>1</sup> Under consideration.

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- Part 4-12: Metallic communication cable test methods Part 4-12: Electromagnetic compatibility (EMC) Coupling attenuation or screening attenuation of connecting hardware Absorbing clamp method
- Part 4-13: Metallic communication cable test methods Part 4-13: Electromagnetic compatibility (EMC) Coupling attenuation of links and channels (laboratory conditions) Absorbing clamp method
- Part 4-14: Metallic communication cable test methods Part 4-14: Electromagnetic compatibility (EMC) Coupling attenuation of cable assemblies (Field conditions) absorbing clamp method

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#### METALLIC COMMUNICATION CABLE TEST METHODS –

# Part 4-3: Electromagnetic compatibility (EMC) – Surface transfer impedance – Triaxial method

### 1 Scope

This part of IEC 62153 determines the screening effectiveness of a cable shield by applying a well-defined current and voltage to the screen of the cable and measuring the induced voltage in order to determine the surface transfer impedance. This test measures only the magnetic component of the transfer impedance.

NOTE The measurement of the electrostatic component (the capacitance coupling impedance) is described in IEC 62153-4-8 [1]<sup>2</sup>.

The triaxial method of measurement is in general suitable in the frequency range up to 30 MHz for a 1 m sample length and up to 100 MHz for a 0,3 m sample length, which corresponds to an electrical length less than about 1/6 of the wavelength in the sample.

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC/TR 62153-4-1:2010, Metallic communication cable test methods – Part 4-1: Electromagnetic compatibility (EMC) – Introduction to electromagnetic (EMC) screening measurements

IEC 60050 (all parts), *International Electrotechnical Vocabulary (IEV)* (available at <a href="http://www.electropedia.org">http://www.electropedia.org</a>)

<sup>2</sup> Numbers in square brackets refer to the bibliography.

### - 2 - IEC 62153-4-3:2013+AMD1:2024 CSV © IEC 2024

### **CONTENTS**

FO	REWC	DRD	5		
INT	RODU	JCTION	7		
1	Scop	Scope			
2	Norm	Normative references			
3	Term	Terms and definitions			
4		siple			
5		methods			
J	5.1 General				
	5.1	Test equipment			
	5.3	Calibration procedure			
	5.4	Sample preparation			
	5.5	Test set-up			
	5.6	Test configurations			
	0.0	5.6.1 General			
		5.6.2 Vector network analyser with S-parameter test set			
		5.6.3 (Vector) network analyser with power splitter			
		5.6.4 Separate signal generator and receiver			
	5.7	Expression of test results			
		5.7.1 Expression	17		
		5.7.2 Test report	17		
6	Test	method A: Matched inner circuit with damping resistor in outer circuit	17		
	6.1	General	17		
	6.2	Damping resistor R <sub>2</sub>	17		
	6.3	Cut-off frequency	18		
	6.4	Block diagram of the set-up	18		
	6.5	Measuring procedure	18		
	6.6	Evaluation of test results	19		
7		method B: Inner circuit with load resistor and outer circuit without damping tor	19		
	7.1	General	19		
	7.2	Cut-off frequency	19		
	7.3	Block diagram of the set-up			
	7.4	Measuring procedure	20		
	7.5	Evaluation of test results	21		
8	Test	method C: (Mismatched)-Short-Short without damping resistor	21		
	8.1	General	21		
	8.2	Cut-off frequency	21		
	8.3	Block diagram of the set-up	22		
	8.4	Measuring procedure	22		
	8.5	Evaluation of test results	22		
Ann	nex A	(normative) Determination of the impedance of the inner circuit	24		
	A.1	Impedance of inner circuit			
Ann	nex B	(normative) Impedance matching adapter			
	B.1	Design of the impedance matching circuit	25		
		B.1.1 General			
		B.1.2 Secondary impedance $Z_2$ lower than primary impedance $Z_1$	25		

IEC 62153-4-3:2013+AMD1:2024 CSV - 3 - © IEC 2024

FINAL VERSION

	B.1.3 Secondary impedance $Z_2$ higher than primary impedance $Z_1$	26
B.2	Frequency response of the impedance matching circuit	26
	B.2.1 General	26
	B.2.2 Measurement using two identical impedance matching adapters	27
	B.2.3 Measurement using the open/short method	27
	B.2.4 Example of a coaxial 50 $\Omega$ to 75 $\Omega$ impedance matching adapter	27
Annex C (normative) Sample preparation for "milked on braid" method		
C.1	General	29
C.2	Coaxial cables	
C.3	Symmetrical and multiconductor cables	
C.4	Verification of the sample preparation with TDR	
Annex D	(informative) Triaxial test set-up depicted as a T-circuit	
D.1	General	
D.2	Scattering parameter $S_{21}$ of the T-circuit	36
	(informative) Cut-off frequency of the triaxial set-up for the measurement of fer impedance	37
E.1	Equivalent circuit	37
E.2	Coupling equations	
E.3	Cut-off frequency	
E.4	Determination of the dielectric permittivity and impedance	
Annex F	(informative) Impact of ground loops on low frequency measurements	43
F.1	General	
F.2	Analysis of the test set-up [3]	43
	(normative) Single pair cables – Conversion of measured mixed mode g parameters to transfer impedance	16
	General	
G.1 G.2	Conversion formula for test method B: Inner circuit with load resistor and	40
G.2	outer circuit without damping resistor	46
Bibliogra	phy	
_		
Figure 1	– Definition of Z <sub>T</sub>	10
	– Definition of Z <sub>F</sub>	
	– Preparation of test sample for coaxial cables	
_	Preparation of test sample for symmetrical cables	
	– Connection to the tube	
	<ul> <li>Test set-up using a vector network analyser with the S-parameter test set</li> </ul>	
_	– 50 $\Omega$ power splitter, 2- and 3-resistor types	
	<ul><li>Test set-up using a network analyser (NA) and a power splitter</li></ul>	
Figure 9	<ul> <li>Test set-up using a signal generator and a receiver</li> </ul>	16
Figure 10	) – Test set-up using a signal generator and a receiver with feeding resistor	17
Figure 1	l – Test set-up (principle)	18
Figure 12	2 – Test set-up (principle)	20
	3 – Test set-up (principle)	
	1 – Impedance matching for $Z_2 < Z_1$	
	2 – Impedance matching for $Z_2 > Z_1$	
	$z$ – impedance matching for $z_2 > z_1$	
ı⁻ıguıte D.	5 - Coariai iiihedance matching adabteis (50 77 to 75 77)	∠/

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Figure B.4 – Attenuation of 50 $\Omega$ to 75 $\Omega$ impedance matching adapter	28
Figure C.1 – Coaxial cables: preparation of cable end "A" <i>(1 of 2)</i>	30
Figure C.2 – Coaxial cables: preparation of cable end "B"	32
Figure C.3 – Symmetrical cables: preparation of cable end "A" (1 of 2)	33
Figure C.4 – Symmetrical cables: preparation of cable end "B"	34
Figure C.5 – Typical resonance of end "A"	35
Figure C.6 – Typical resonance of end "B"	35
Figure D.1 – Triaxial set-up depicted as a T-circuit	36
Figure E.1 – Equivalent circuit of the triaxial set-up	37
Figure E.2 – Frequency response of the triaxial set-up for different load conditions	39
Figure E.3 – Measurement of $S_{11}$ of the outer circuit (tube) having a length of 50 cm	41
Figure F.1 – Triaxial test set-up	43
Figure F.2 – Equivalent circuits of the triaxial set-up	44
Figure F.3 – Example showing the impact of the measurement error	45

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- b) formulas to calculate the maximum frequency up to which the different test configurations can be used are included (Annex E: Cut-off frequency of the triaxial set-up for the measurement of the transfer impedance);
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- Part 4-1: Metallic communication cable test methods Part 4-1: Electromagnetic compatibility (EMC) Introduction to electromagnetic (EMC) screening measurements
- Part 4-2: Metallic communication cable test methods Part 4-2: Electromagnetic compatibility (EMC) Screening and coupling attenuation Injection clamp method
- Part 4-3: Metallic communication cable test methods Part 4-3: Electromagnetic compatibility (EMC) Surface transfer impedance Triaxial method
- Part 4-4: Metallic communication cable test methods Part 4-4: Electromagnetic compatibility (EMC) Shielded screening attenuation, test method for measuring of the screening attenuation as up to and above 3 GHz
- Part 4-5: Metallic communication cables test methods Part 4-5: Electromagnetic compatibility (EMC) Coupling or screening attenuation Absorbing clamp method
- Part 4-6: Metallic communication cable test methods Part 4-6: Electromagnetic compatibility (EMC) Surface transfer impedance Line injection method
- Part 4-7: Metallic communication cable test methods Part 4-7: Electromagnetic compatibility (EMC) Test method for measuring the transfer impedance and the screening or the coupling attenuation Tube in tube method
- Part 4-8: Metallic communication cable test methods Part 4-8: Electromagnetic compatibility (EMC) Capacitive coupling admittance
- Part 4-9: Metallic communication cable test methods Part 4-9: Electromagnetic compatibility (EMC) Coupling attenuation of screened balanced cables, triaxial method
- Part 4-10: Metallic communication cable test methods Part 4-10: Electromagnetic compatibility (EMC) Shielded screening attenuation test method for measuring the screening effectiveness of feed-throughs and electromagnetic gaskets double coaxial method
- Part 4-11: Metallic communication cable test methods Part 4-11: Electromagnetic compatibility (EMC) Coupling attenuation or screening attenuation of patch cords, coaxial cable assemblies, pre-connectorized cables Absorbing clamp method

<sup>1</sup> Under consideration.

FINAL VERSION

- 8 - IEC 62153-4-3:2013+AMD1:2024 CSV © IEC 2024

- Part 4-12: Metallic communication cable test methods Part 4-12: Electromagnetic compatibility (EMC) Coupling attenuation or screening attenuation of connecting hardware Absorbing clamp method
- Part 4-13: Metallic communication cable test methods Part 4-13: Electromagnetic compatibility (EMC) Coupling attenuation of links and channels (laboratory conditions) Absorbing clamp method
- Part 4-14: Metallic communication cable test methods Part 4-14: Electromagnetic compatibility (EMC) Coupling attenuation of cable assemblies (Field conditions) absorbing clamp method

IEC 62153-4-3:2013+AMD1:2024 CSV - 9 - © IEC 2024

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#### METALLIC COMMUNICATION CABLE TEST METHODS –

# Part 4-3: Electromagnetic compatibility (EMC) – Surface transfer impedance – Triaxial method

### 1 Scope

This part of IEC 62153 determines the screening effectiveness of a cable shield by applying a well-defined current and voltage to the screen of the cable and measuring the induced voltage in order to determine the surface transfer impedance. This test measures only the magnetic component of the transfer impedance.

NOTE The measurement of the electrostatic component (the capacitance coupling impedance) is described in IEC 62153-4-8 [1]<sup>2</sup>.

The triaxial method of measurement is in general suitable in the frequency range up to 30 MHz for a 1 m sample length and up to 100 MHz for a 0,3 m sample length, which corresponds to an electrical length less than about 1/6 of the wavelength in the sample.

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC/TR 62153-4-1:2010, Metallic communication cable test methods – Part 4-1: Electromagnetic compatibility (EMC) – Introduction to electromagnetic (EMC) screening measurements

IEC 60050 (all parts), *International Electrotechnical Vocabulary (IEV)* (available at <a href="http://www.electropedia.org">http://www.electropedia.org</a>)

<sup>2</sup> Numbers in square brackets refer to the bibliography.